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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: ITABASHI, et al.

3 / IDS
E. Willis
9-19-02

Filed: September 25, 2001

For: SEMICONDUCTOR DEVICE HAVING WIRES AND INSULATOR LAYERS WITH VIA-STUDS

INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR 1.97 AND 1.98

Assistant Commissioner for Patents
Washington, D.C. 20231

September 25, 2001

Sir:

Pursuant to Applicants' duty of disclosure, enclosed please find a List, on a form substantially equivalent to Form PTO-1449, of documents cited in connection with prior application Serial No. 09/317,955, filed May 25, 1999.

Since No. 09/317,955, is being relied upon in the above-identified application under 35 USC 120, copies of the listed documents are not enclosed. See 37 CFR 1.98(d).

This Information Disclosure Statement is being submitted concurrently with the filing of the above-identified application. Accordingly, requirements of 37 CFR 1.97(b) are satisfied.

Insofar as these documents on the enclosed List are not in English, the following additional comments are submitted under 37 CFR 1.98(a)(3):

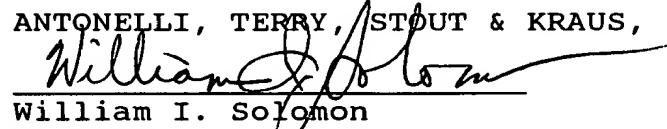
- (1) An English translation of a Taiwanese Office Action, referencing the listed Japanese patent documents, was submitted with the Information Disclosure Statement filed May 2, 2001, in No. 09/317,955;

- (2) In connection with Japanese Patent Document No. 8-83796, note European Patent Specification No. EP692,554, containing a corresponding disclosure; and
- (3) JP8-83796 fails to disclose the feature of the present invention about how to produce each layer on a via hole; and JP9-316651 describes plating for Sn-Zn alloy, so that the feature and purpose of JP9-316651 are different from that in the above-identified application.

In view of all of the foregoing, it is respectfully submitted that all applicable requirements of 37 CFR 1.97 and 1.98 have been satisfied, in connection with all documents on the enclosed List. Accordingly, consideration of the listed documents, upon examination of the above-identified application, is respectfully requested.

To the extent necessary, Applicants petition for an extension of time under 37 CFR § 1.136. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to the Deposit Account No. 01-2135 (Case No. 501.37226VX1) and please credit any excess fees to such Deposit Account.

Respectfully submitted,

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WIS/slk
Enclosures

Form PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DKT. NO.
501.37226VX1

SERIAL NO.

INFORMATION DISCLOSURE STATEMENT
BY APPLICANT

(Use several sheets if necessary)

APPLICANT
ITABASHI, et al.FILING DATE
September 25, 2001

GROUP

USPTO
09/25/01
jc973

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
AA	5,891,513	4-6-99	Dubin, et al.			
AB	4,985,750	1-15-91	Hoshino			
AC	5,674,787	10-7-97	Zhao, et al.			
AD	5,723,387	3-3-98	Chen			
AE	5,384,284	1-24-95	Doan, et al.			
AF	6,093,647	6-00	Yu, et al.			
AG	5,660,706	8-97	Zhao, et al.			
AH						
AI						
AJ						
AK						
AL						

FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation/ Abstract	
						Yes	No
AM	692554	1-17-96	Europe				
AN	8-83796	3-26-96	Japan				
AO	9-316651	12-9-97	Japan				
AP							
AQ							
AR							
AS							
AT							

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

AU	
AV	
AW	
AX	
AY	
AZ	

Examiner _____ Date Considered _____